

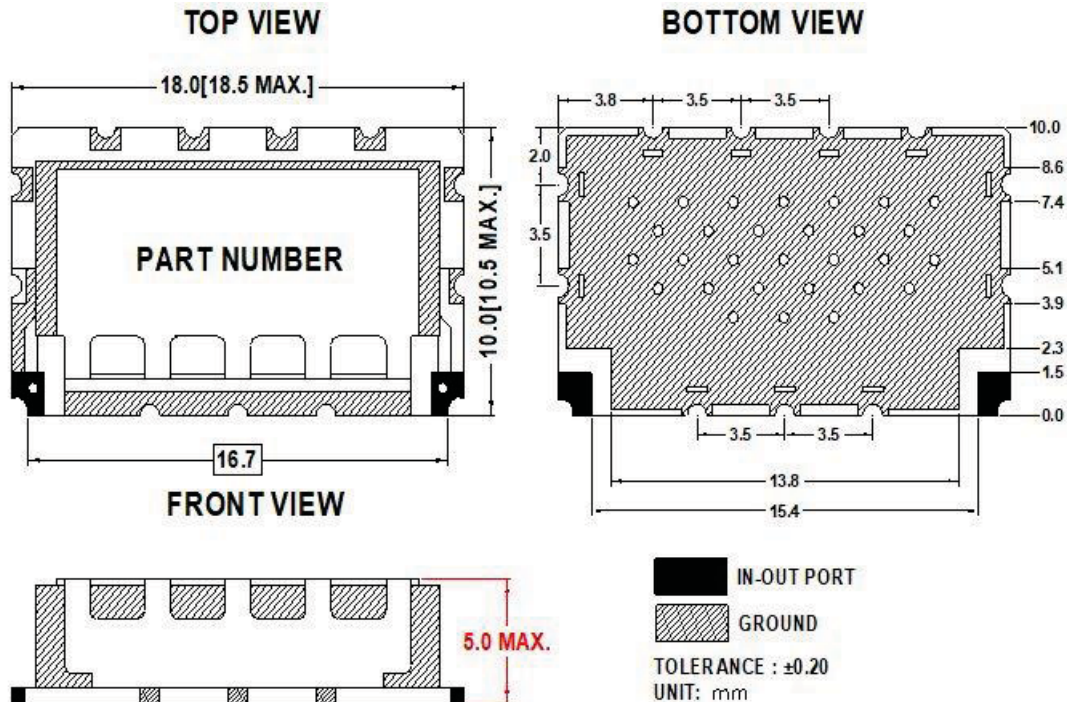
# SPECIFICATION

Written by	Checked by	Approval
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## ELECTRICAL SPECIFICATIONS

ITEM	SPEC	UNIT
1	Center freq	3312.5
2	Bandwidth [1dB BW]	$f_0 \pm 60.0$ [3252.5~3372.5]
3	Insertion Loss in BW	2.5
4	Ripple in BW	1.5
5	Return Loss in BW	
6	V S W R in BW	2.0
7	Attenuation (Absolute Value)	43.0 dB min. @ $f_0 \pm$ [3000.0 & ] 43.0 dB min. @ $f_0 \pm$ [3600.0 & ]
8	Group Delay Variation	
9	Input Power	1.0
10	In/Out Impedance	50Ω
11	Operation Temperature Range	-40°C to +85°C

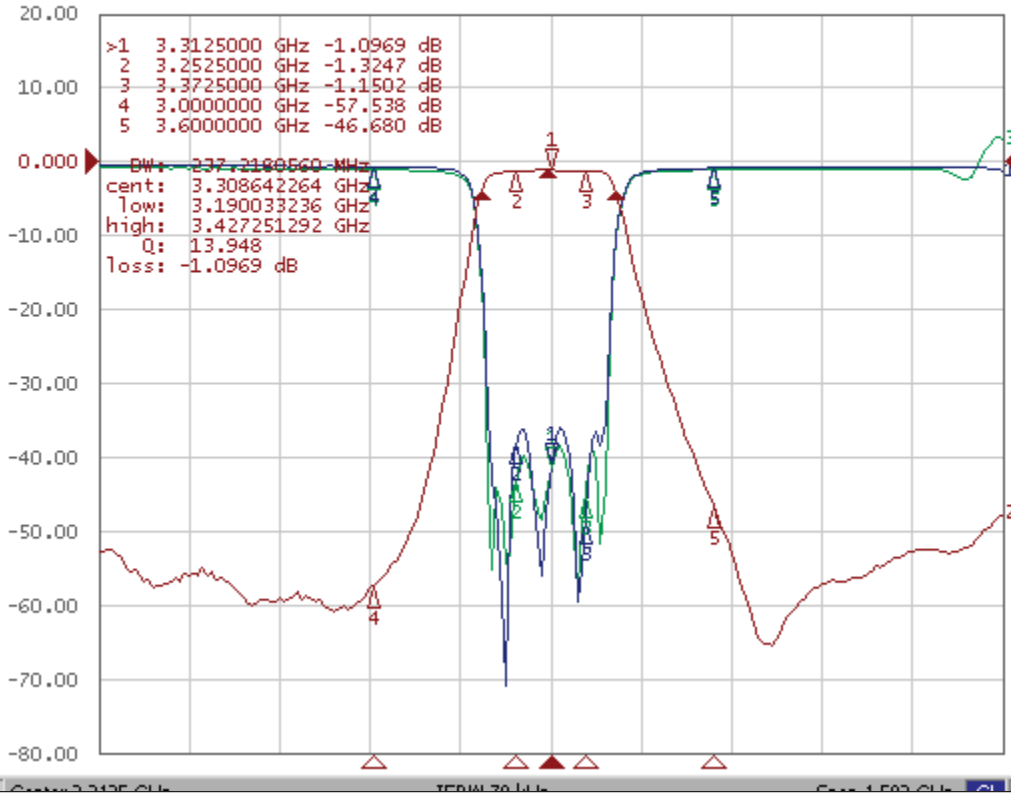
## MECHANICAL SPECIFICATIONS



### PERFORMANCE

1 Active Ch/Trace 2 Response 3 Stimulus 4 Mkr/Analysis 5 Instr State

Tr1 S22 Log Mag 5.000dB/ Ref 0.000dB [F2]  
 Tr2 S23 Log Mag 10.00dB/ Ref 0.000dB [F2]  
 Tr3 S33 Log Mag 5.000dB/ Ref 0.000dB [F2]



Trigger

Hold

Single

Continuous

Hold All Channels

Continuous Disp Channels

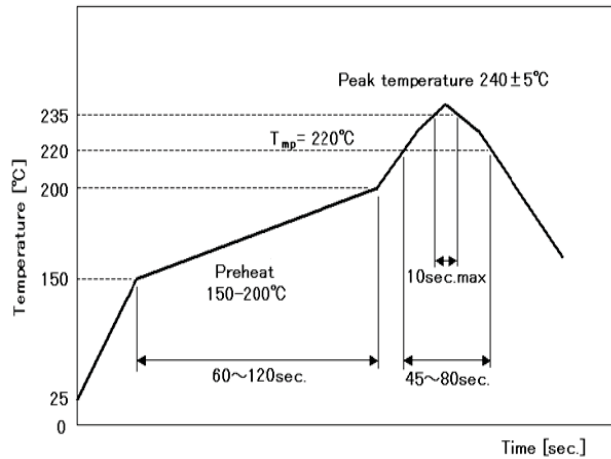
Trigger Source Internal

Trigger Event On Sweep

Trigger Scope All Channel

Restart

### SOLDERING CONDITION



Remark:

1. Please ensure that the good grounding (ground and I/O part area). When the product is used, in order to ensure good grounding ,bottom area after soldering, that need for the side pin to repair welding.
2. Product recommended using SMT process, the above is recommended reflow temperature curve. Because of different substrate and reflow soldering equipment varies , according to the substrate and reflow soldering equipment to confirm the actual temperature curve.
3. If special occasion occurs which needs manual soldering, the temperature should be  $350^\circ\text{C}$  ,but not Over 3 times, and reflow and manual soldering should not be over 3 times.